

HSU276A

Silicon Schottky Barrier Diode for Mixer

REJ03G0613-0200
(Previous: ADE-208-837A)
Rev.2.00
Apr 28, 2005

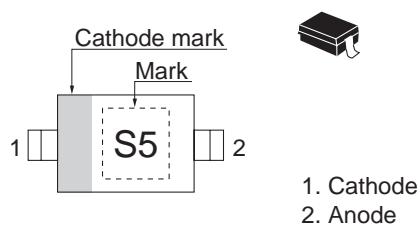
Features

- High forward current, Low capacitance.
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSU276A	S5	URP	PTSP0002ZA-A (URP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V _{RRM}	5	V
Reverse voltage	V _R	3	V
Average rectified current	I _o	30	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V _R	3.0	—	—	V	I _R = 1 mA
Reverse current	I _R	—	—	50	μA	V _R = 0.5 V
Forward current	I _F	35	—	—	mA	V _F = 0.5V
Capacitance	C	—	—	0.85	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Note: Failure criterion ; I_R > 100 μA at V_R = 0.5 V

Main Characteristic

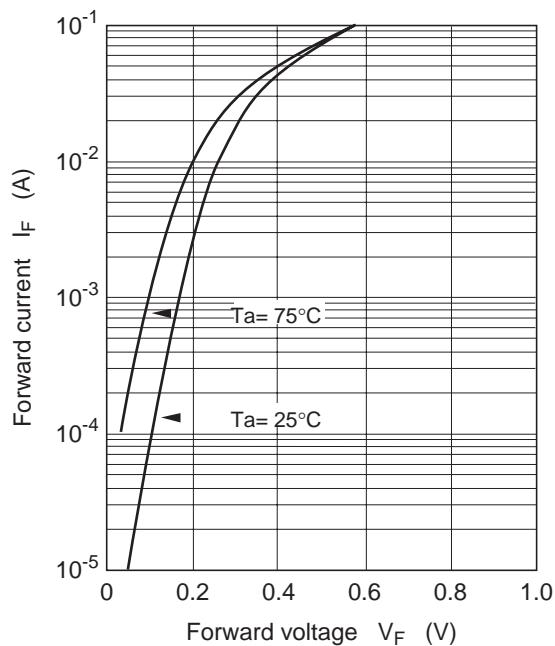


Fig.1 Forward current vs. Forward voltage

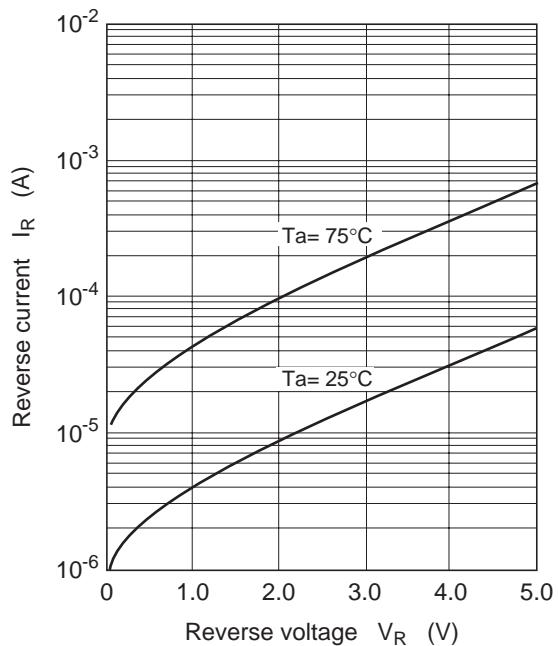


Fig.2 Reverse current vs. Reverse voltage

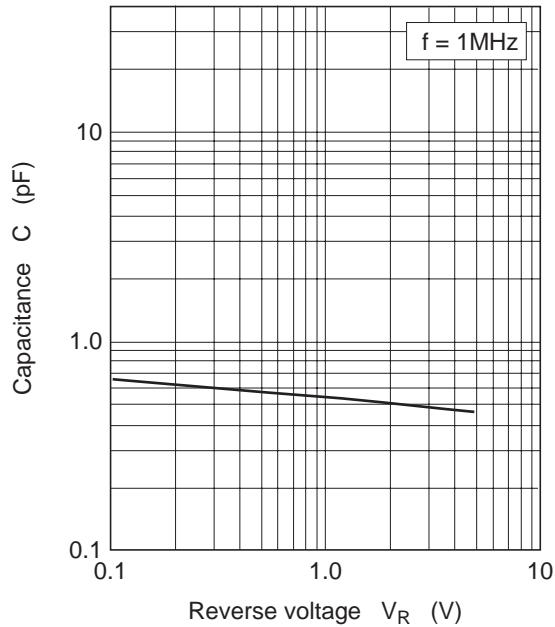
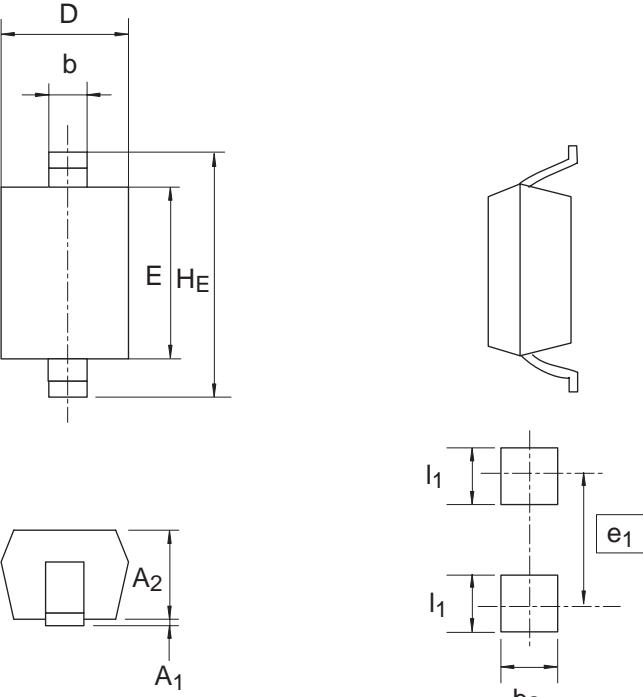


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
SC-76A	PTSP0002ZA-A	URP / URPV	0.004g



Top view diagram of the package showing dimensions D, b, E, and H_E. It also shows a side view of the package and a detailed view of the lead frame with dimensions l₁, b₂, and e₁.

Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A ₁	0	-	0.1
A ₂	0.75	0.90	1.05
b	0.15	0.30	0.45
D	1.10	1.25	1.40
E	1.55	1.70	1.85
H _E	2.35	2.50	2.65
b ₂	-	0.80	-
e ₁	-	2.30	-
l ₁	-	0.80	-

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